

Applications of Interoperable Databases and Data Models in Production Flows at LSI Logic

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LSI LOGIC



Agenda

- Background
- RapidChip™ with the RapidWorx™ design kit
- Bond Application
- Summary

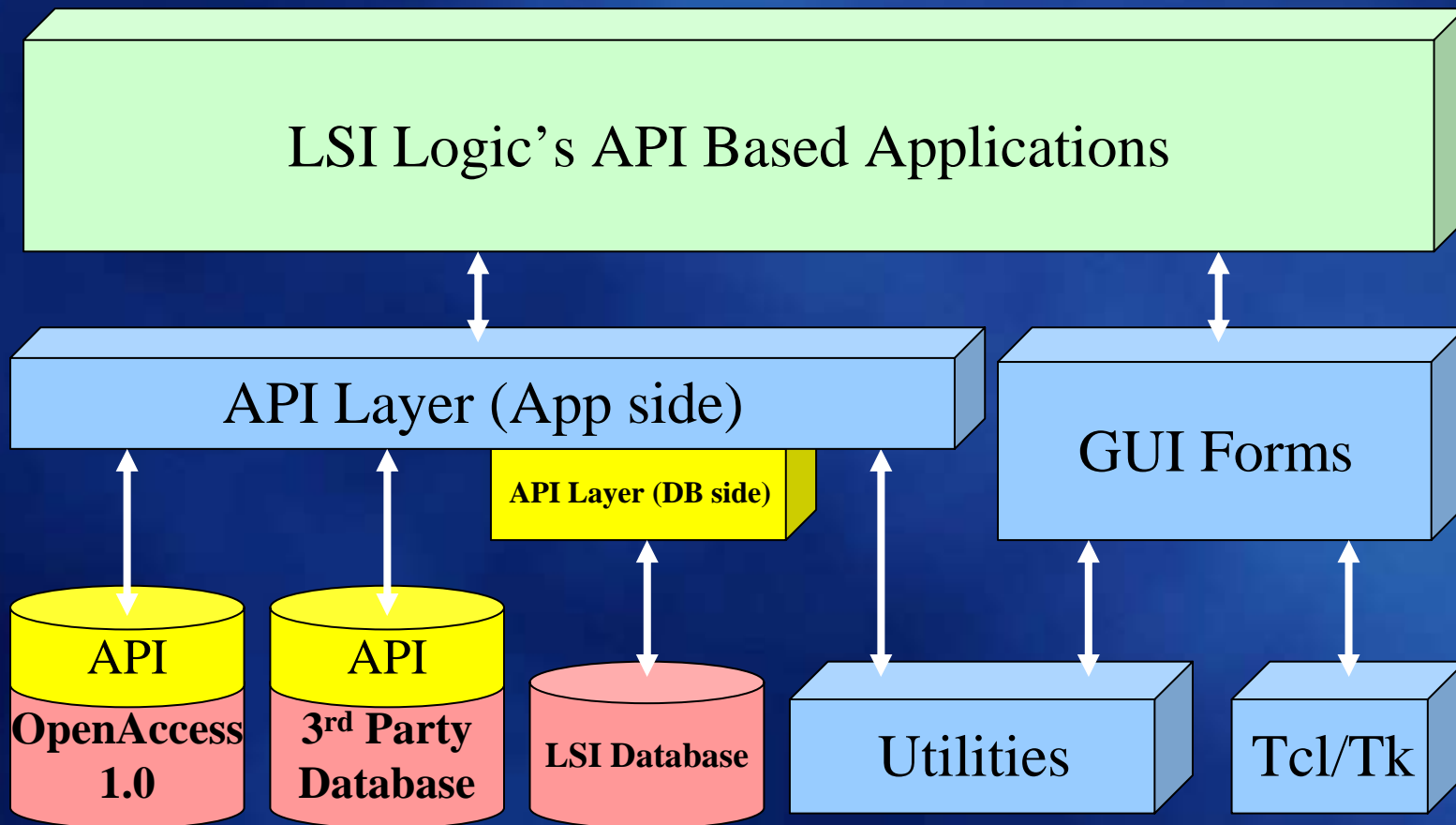


Background

- LSI Logic maintains several internal databases for design kits
 - Propriety in nature and specific for feature needs
 - Maintaining propriety databases requires an investment for development and support
- LSI Logic uses commercial databases
 - Provide value add applications on commercial offerings
 - No one vendor supplies the necessary features required
- LSI Logic began investigation of OpenAccess initiative and technology late 2001
 - Initially ported a GDSII application on OA1.0
 - Determined viability of OpenAccess and proceeded to develop future RapidWorx™ design kit on OpenAccess for RapidChip™ product



Initial Investigation



GDSII Benchmarking

- LSI created a GDSII to OA converter
 - Quickest way to populate testcases
 - Centralizes OA database for translators
 - GDSII -> OA, OA -> GDSII
 - DEF -> OA, OA -> DEF
 - Etc.
- Sample data sets show good results
 - 3x file size reduction
 - Program memory usage reasonable
 - Program runtimes reasonable



GDSII Benchmarking

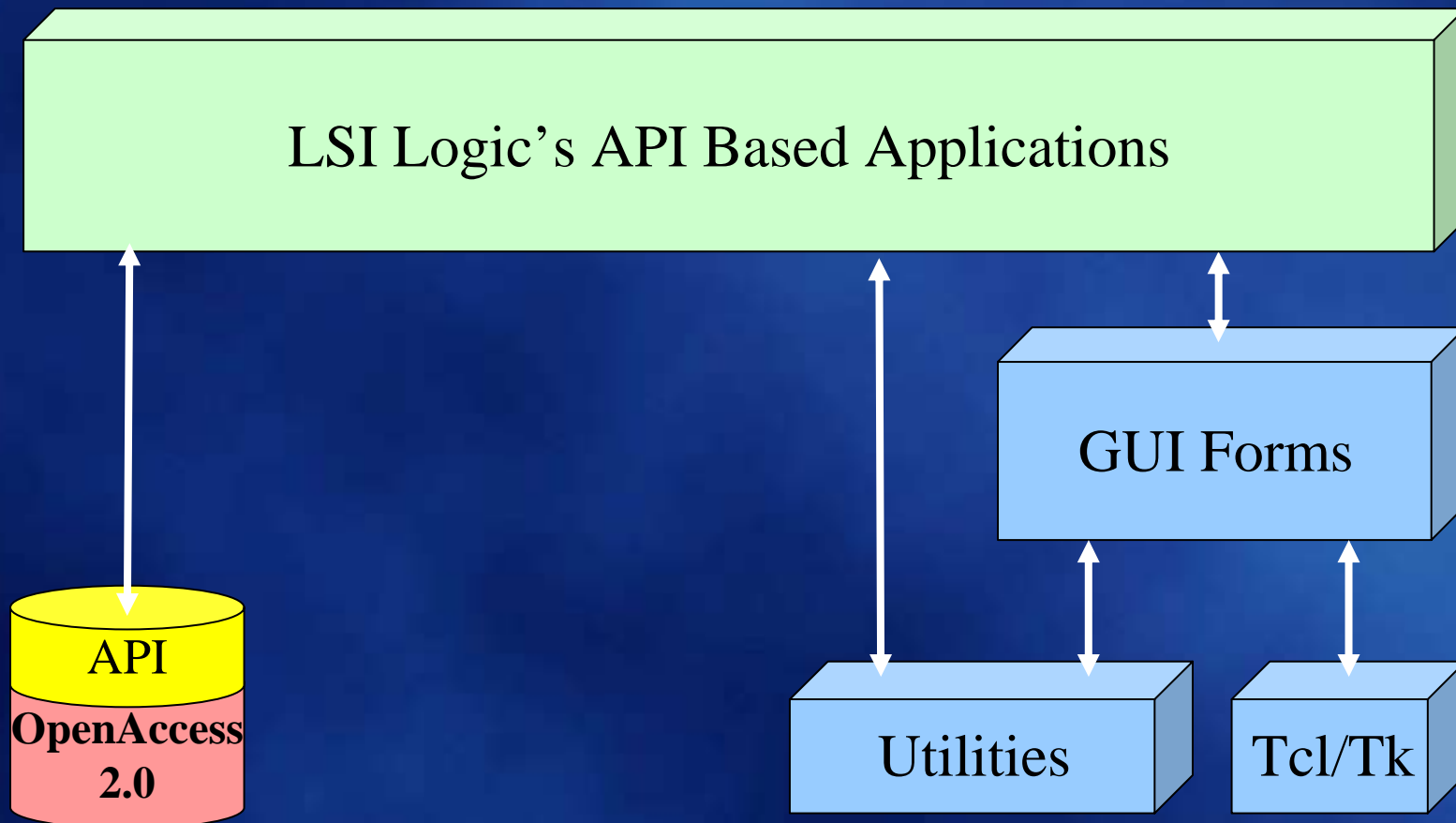
	Number of Records	Read Time (ms)	Elapased time (ms)	GDS Size (KB)	OA Size (KB)	Ratio
Design 1	464078	11456	16944	3684	1434	2.6
Design 2	5177017	70101	76760	42690	14215	3.0
Design 3	5774428	77201	85933	49296	16087	3.1
Design 4	6758148	75459	82899	54408	18263	3.0
Design 5	7078607	87235	94806	57104	19222	3.0
Design 6	7186254	88538	96038	58050	19405	3.0
Design 7	8405195	105321	111430	67688	22593	3.0

Run on

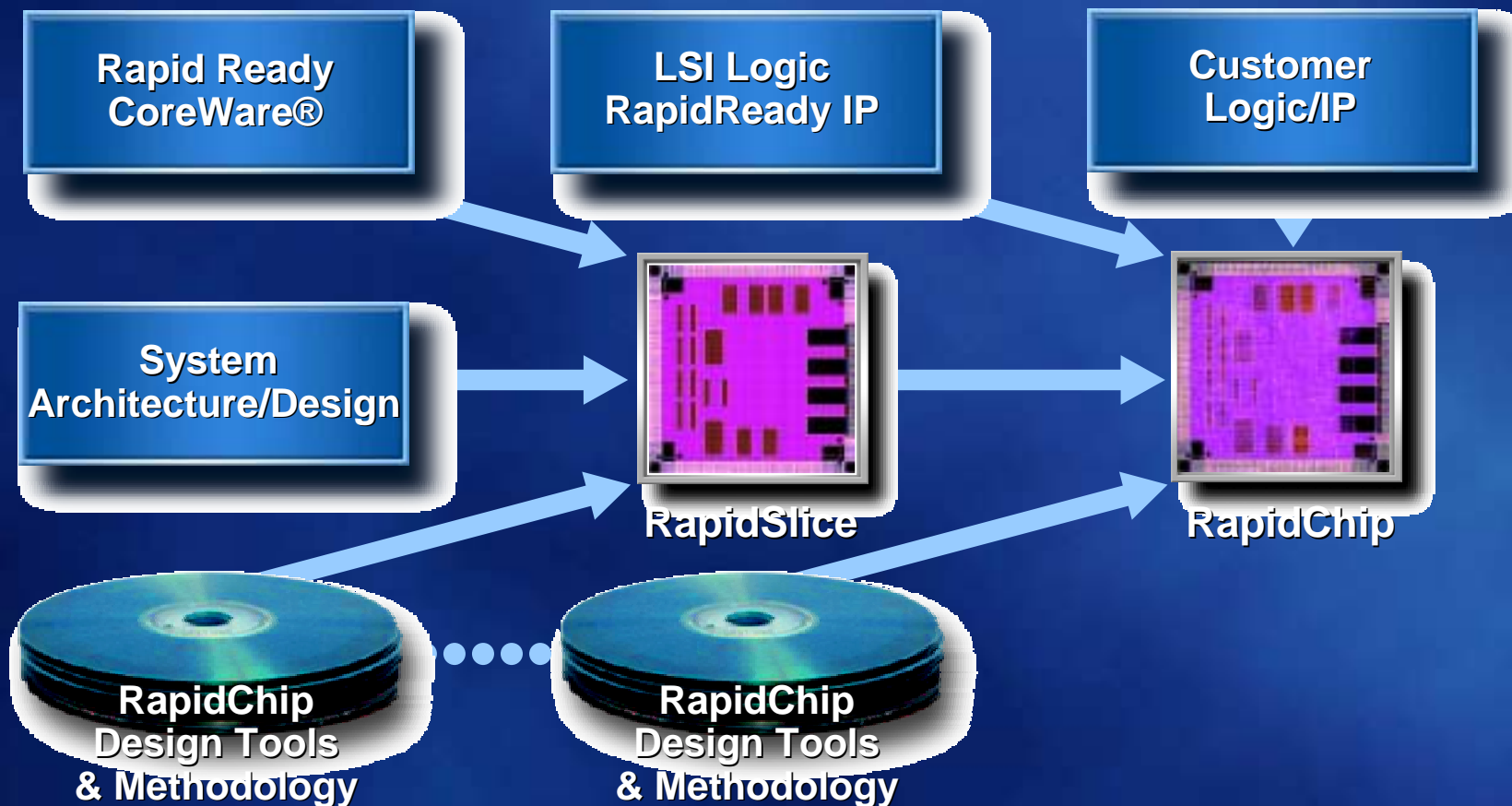
Pentium III 700MHz processor
256MBytes of memory
Win2000 operation system



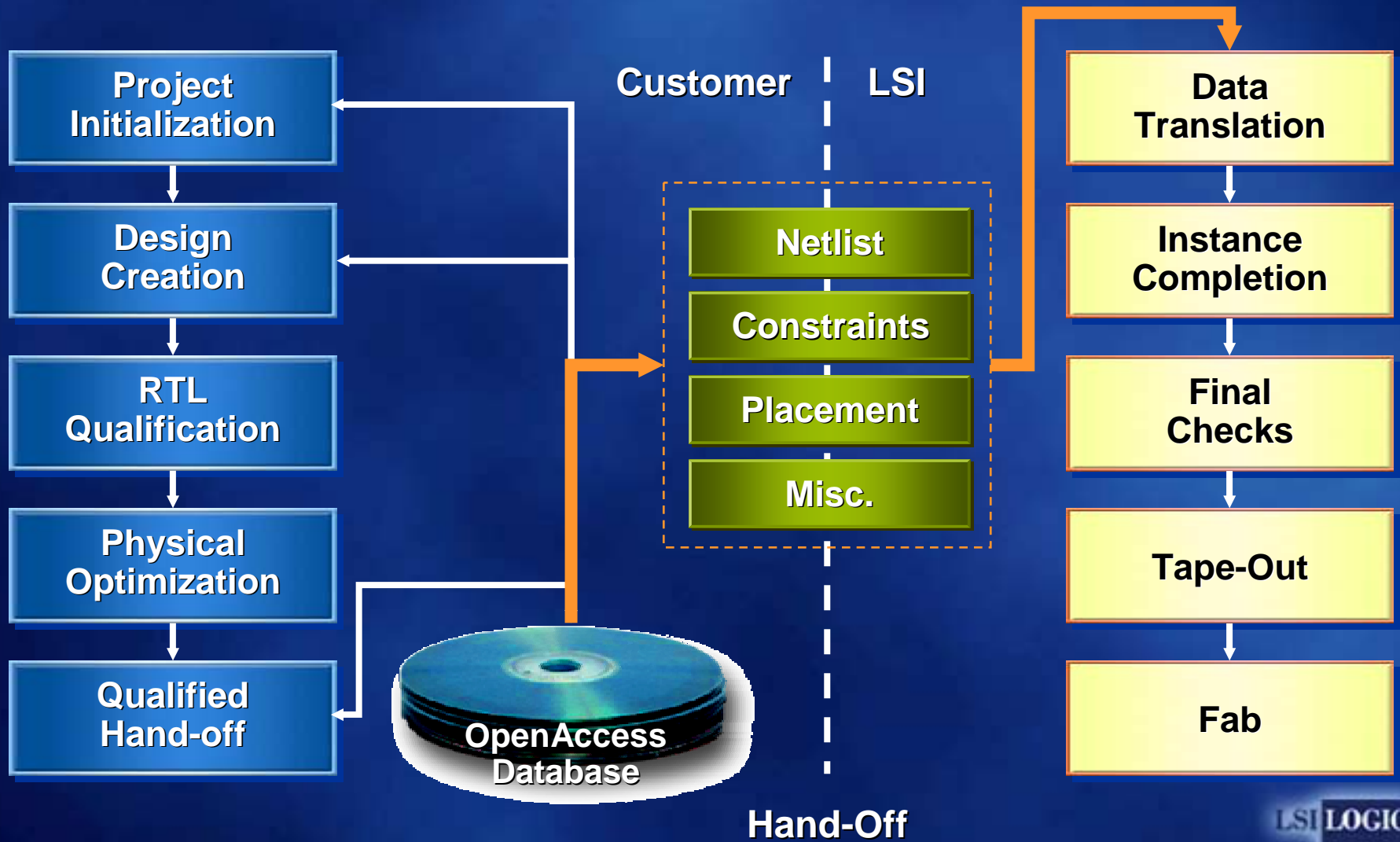
Natively Using OpenAccess



RapidChip™ Product Architecture



RapidWorx™ High Level Design Flow View



RapidChip™ Design Steps

1. Project Initialization

- Slice Selection
- Select Soft + Firm IP
- Instance Initialization
- **View Slice**

2. Design Creation

- RTL/Constraint/Floorplan Creation
 - **RapidBuilder**
- Review/Optimization Floorplan
 - Unconstrained Synthesis
 - **Initialize Floorplan/Personalize Slice**
 - **Edit Floorplan**
- Prepare for Physical Synthesis
 - **Write DEF**

3. RTL Qualification

- RapidPRO

4. Physical Optimization

- Physical Synthesis

5. Qualified Netlist Handoff

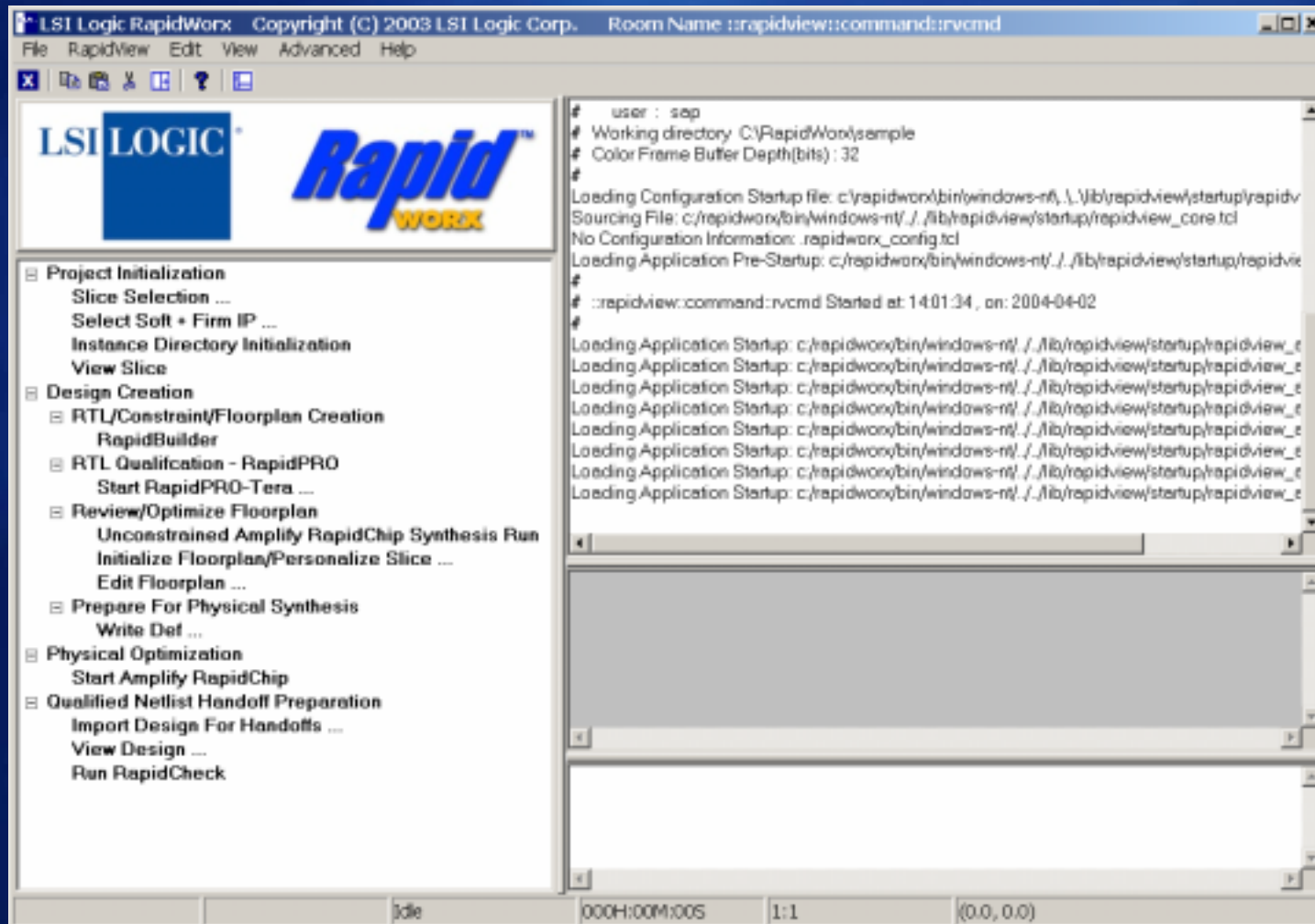
- **Import Design for Handoffs**
- **View Design**
- **RapidCheck**

Current OA base tools
Future OA base tools



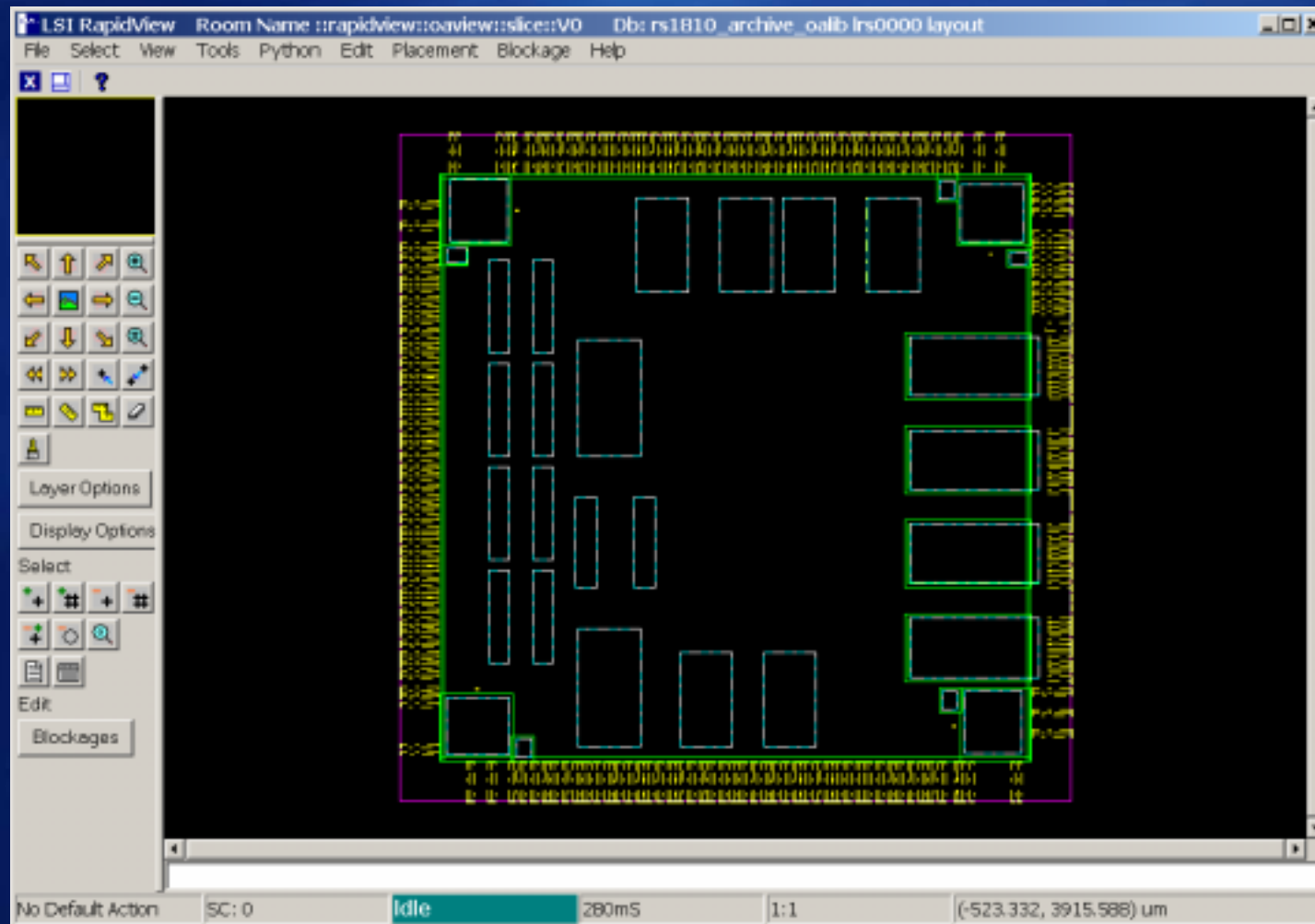


Design Cockpit based on OpenAccess

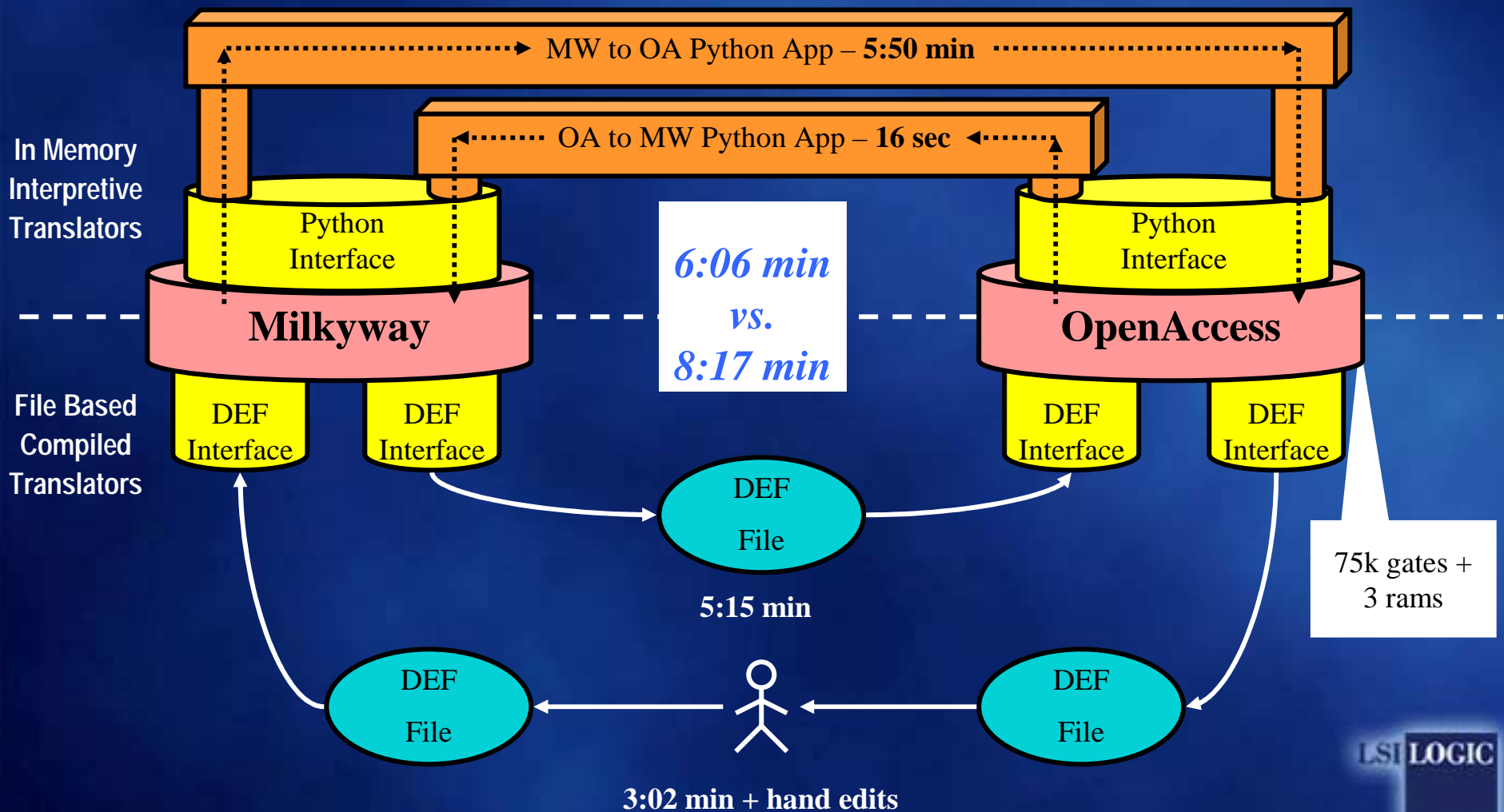




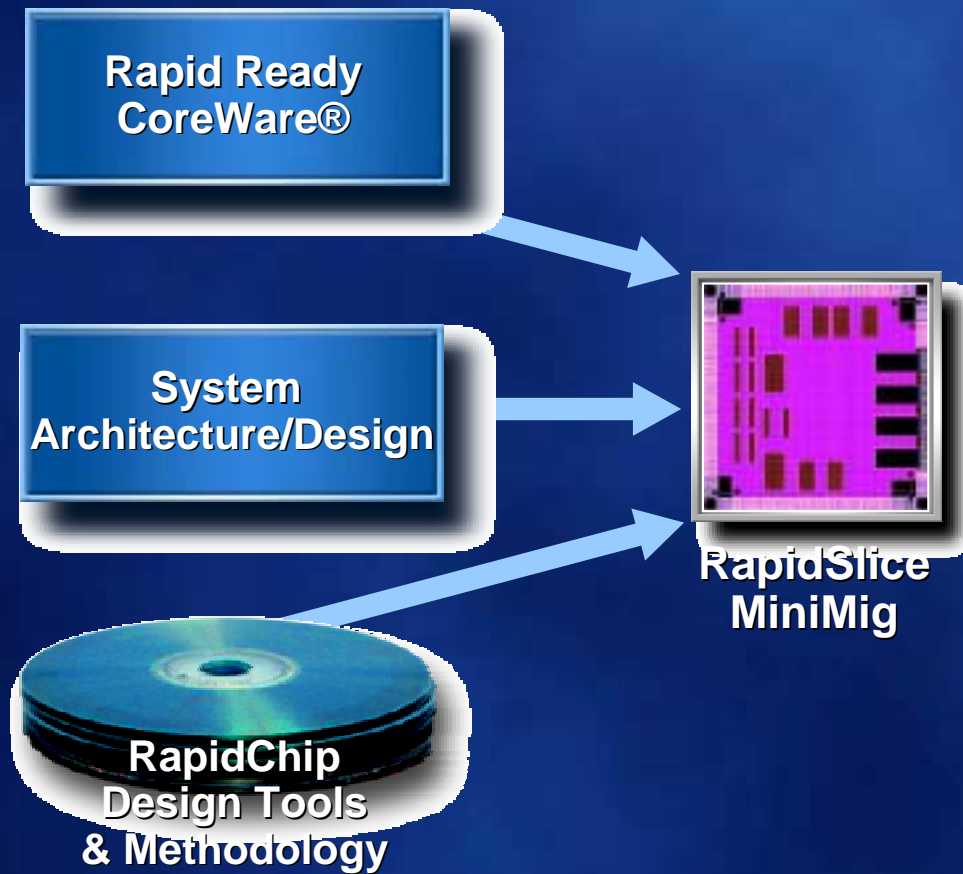
Design Viewer based on OpenAccess



Post Handoff Data Translation Example



RapidSlice “MiniMig”

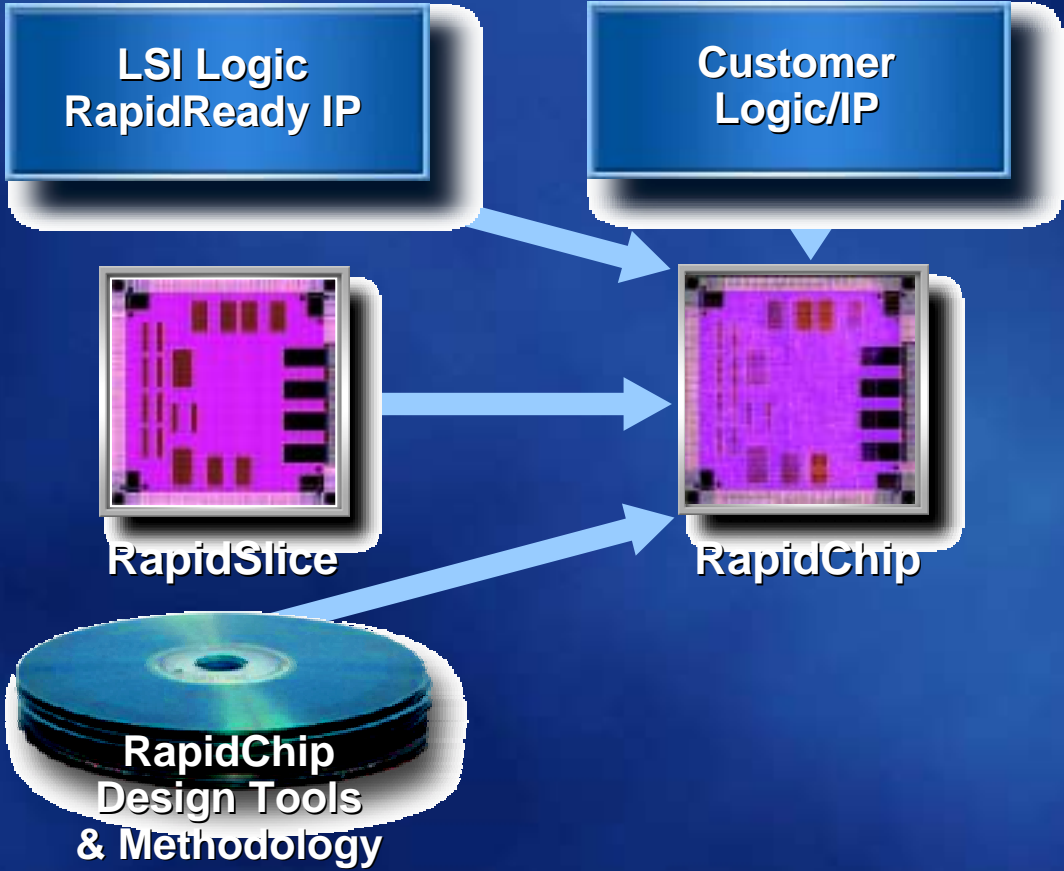


RapidSlice “MiniMig”

- Slice Gates
 - 1.5M Customer usable gates
- Slice Memories
 - (6) 2K word x 36 bit 2rw
 - (8) 1K word x 36 bit 2rw
 - (16) 256 word x 36 bit 2rw
 - (4) 4K word x 36 bit 1rw
- Slice Metal Programmable PLL's
 - (4) 100-500Mhz
- Slice Configurable I/Os
 - 390 Customer configurable
 - 660 Wirebond package



RapidChip™ Customer Design



RapidChip™ on MiniMig

- Slice Gates
 - 1.5M Customer usable gates
- Slice Memories
 - (6) 2K word x 36 bit 2rw
 - (8) 1K word x 36 bit 2rw
 - (16) 256 word x 36 bit 2rw
 - (4) 4K word x 36 bit 1rw
- Slice Metal Programmable PLL's
 - (4) 100-500Mhz
- Slice Configurable I/Os
 - 390 Customer configurable
 - 660 Wirebond package
- Customer Design Gates
 - 84K gates
- Customer Design Memories
 - (4) 2K word x 36 bit 2rw
- Customer Design PLL's
 - (2) 106 Mhz
- Customer Design I/Os
 - 204 2.5v BiDirect



RapidChip™ on MiniMig

Unused PLL

Used PLL

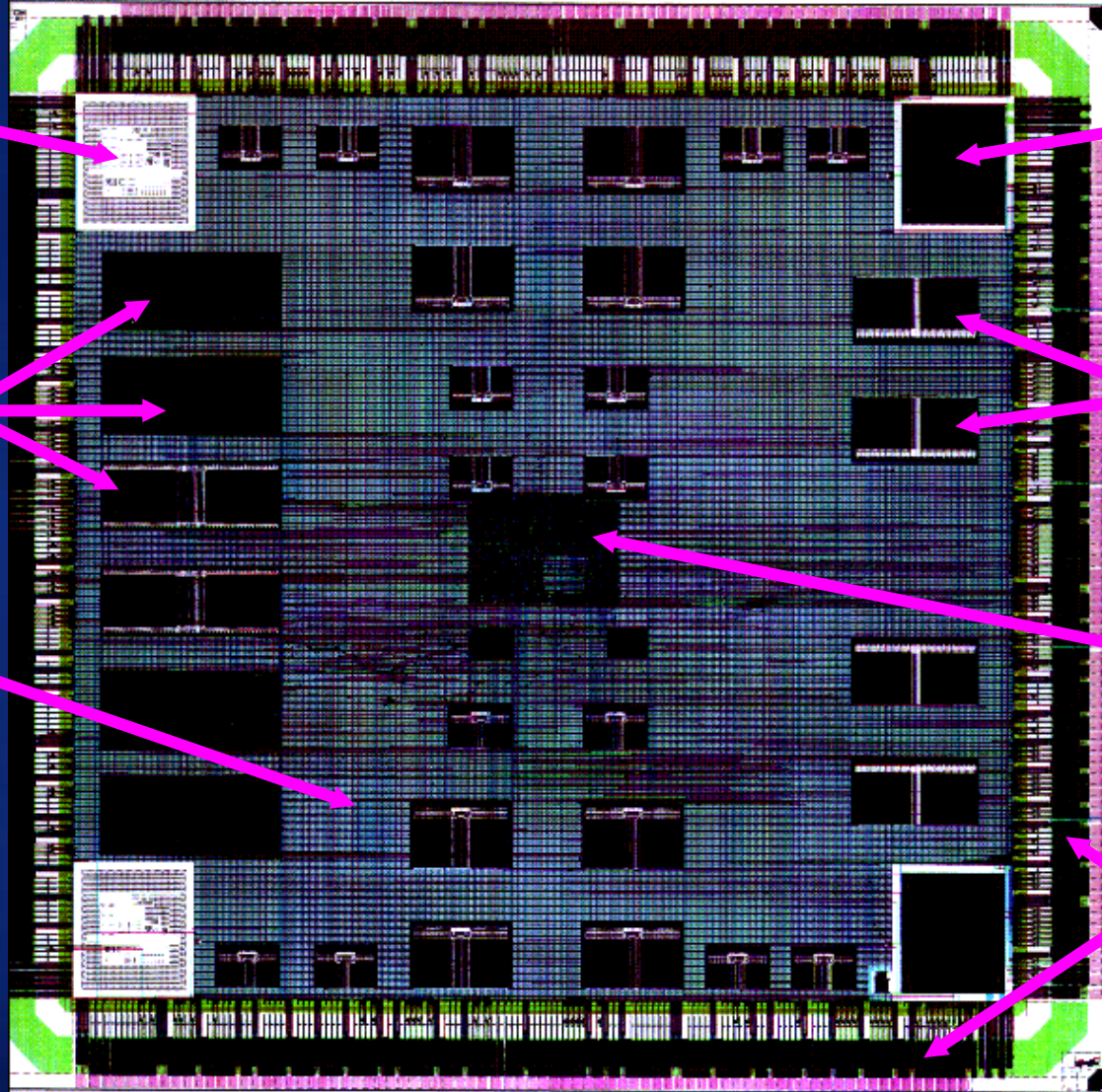
Unused Memories

Used Memories

Unused Gates

Used Gates

Used I/Os



RapidChip™ Integrator Family

- http://lsilogic.com/products/rapidchip_platform_asic

	Integrator Family (0.11µm)						
	RC11Si210	RC11Si211	RC11Si220	RC11Si221	RC11Si230	RC11Si231	RC11Si240
Available Gates (M)	2.4	4.1	3.4	5.4	5	7	6.3
Min-Max Usable Gates (M)	0.8-1.0	1.6-2.4	1.0-2.0	2.1-3.1	1.9-2.9	2.6-4.0	2.4-3.6
RAM: 111 (1rw) 2k x 72	0	0	0	0	0	0	6
RAM: 111 (1rw) 1k x 36	16	16	16	16	16	16	10
RAM: 222 (2rw) 512 x 36	28	28	12	12	16	16	16
RAM: 222 (2rw) 1k x 36	0	0	8	8	12	12	12
RAM: 222 (2rw) 2k x 36	0	0	12	12	16	16	24
Total RAM Bits (M)	1.1	1.1	2	2	2.5	2.5	3.7
100MHz to 500MHz PLLs	4	4	4	4	4	4	4
Packages							
252 BGA - 171 Max I/O	171	171	171	0	0	0	0
480 BGA - 355 Max I/O	355	355	355	355	355	0	0
672 BGA - 491 Max I/O	0	491	491	491	491	491	491
896 BGA - 683 Max I/O	0	0	0	683	683	683	683
1152 BGA - 803 Max I/O	0	0	0	0	0	803	803



Silicon Proven Products Delivered Rapidly

Take A 3Gb/s Spin With Seagate's Savvio Drive...

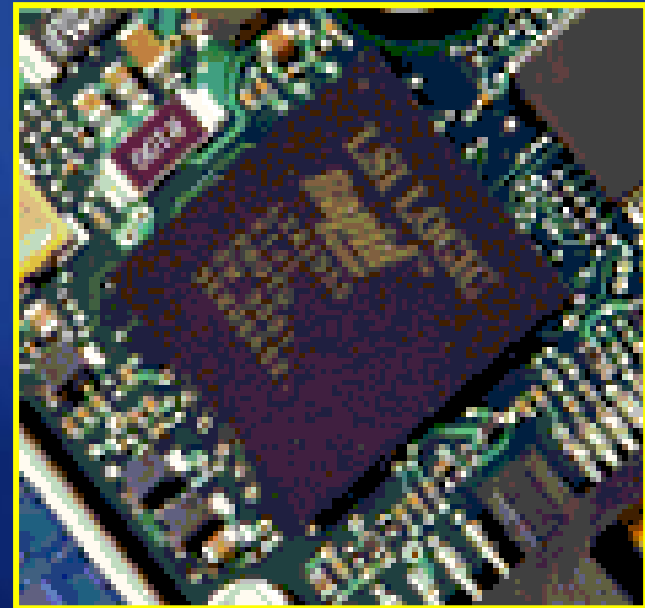
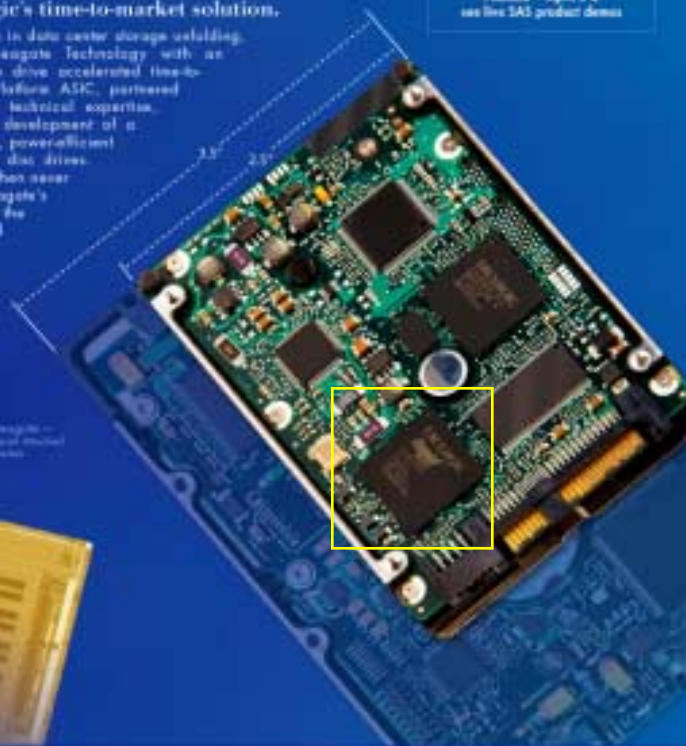
Powered by LSI Logic's time-to-market solution.

With regulatory changes in data center storage solidifying, LSI Logic approached Seagate Technology with an innovative new solution to drive accelerated time-to-market. The RapidChip™ Platform ASIC, partnered with Seagate's renowned technical expertise, would enable streamlined development of a new generation of compact, power-efficient Serial Attached SCSI hard disc drives. Seagate looked hard, and then never looked back. The result: Seagate's groundbreaking Savvio™, the industry's first 2.5-inch Serial Attached SCSI disc drive.

Visit LSI Logic at Booth 604
Storage Networking World
Phoenix • April 5-8
see live SAS product demos



LSI Logic and Seagate -
Partnering to create
the industry's first 2.5-inch SAS



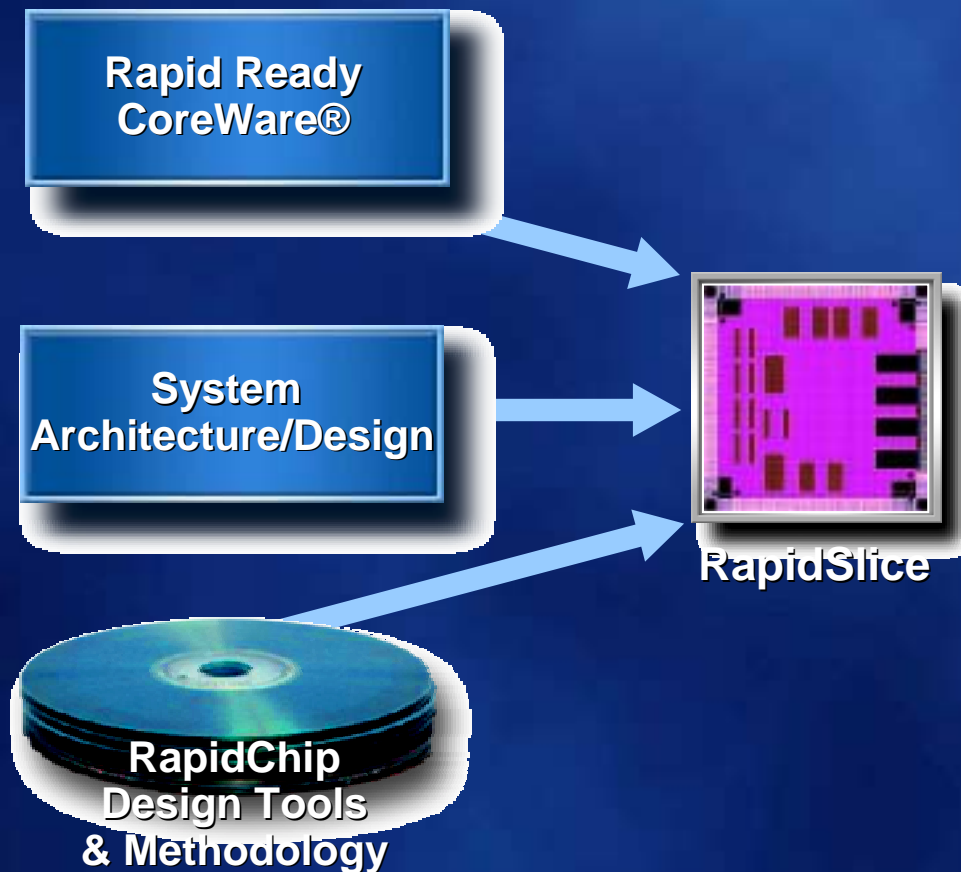
KREME FAMILY INTEGRATOR FAMILY FOUNDATION FAMILY

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Rapid
CHIP
by LSI Logic

LSI LOGIC

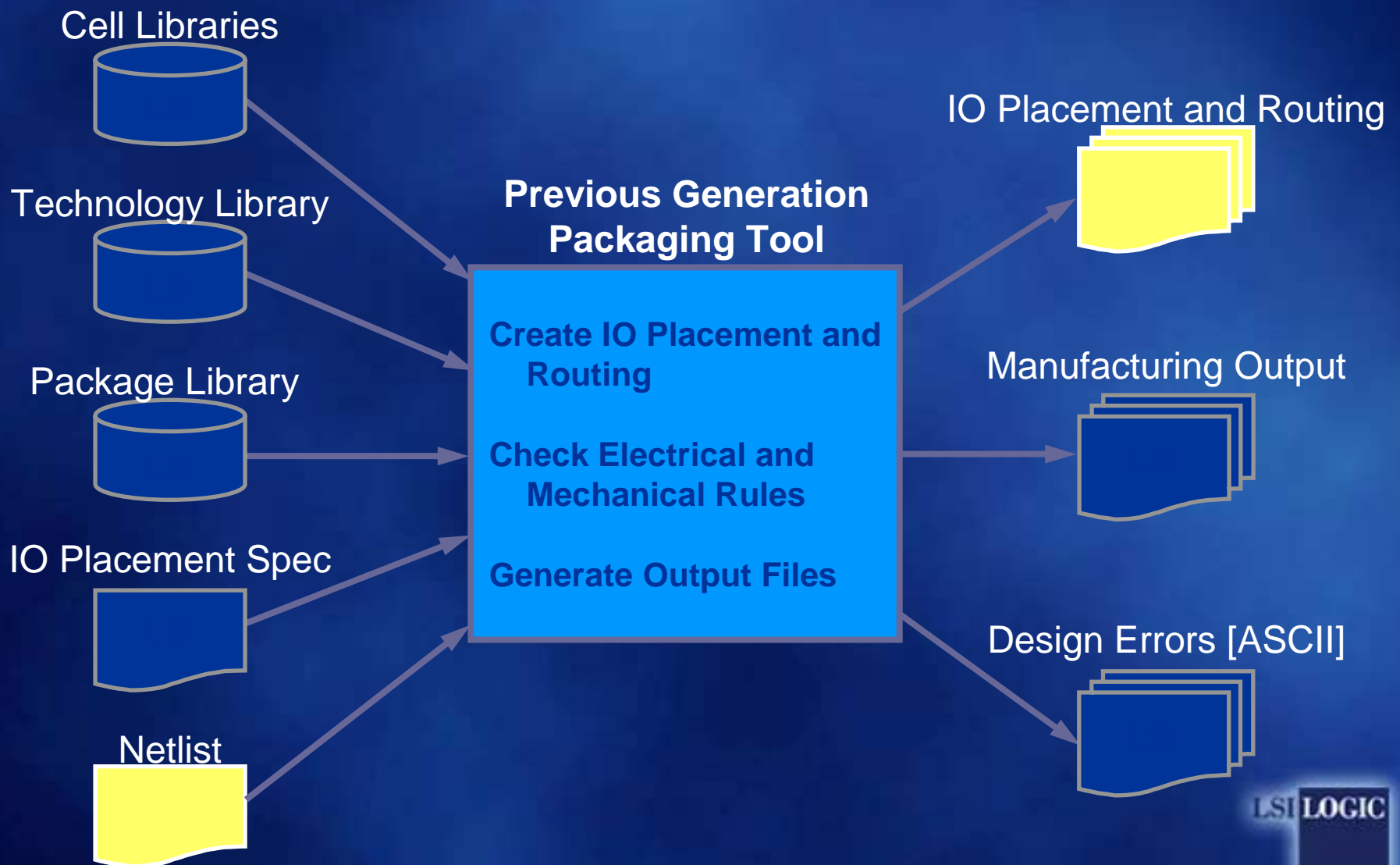
RapidSlice Creation



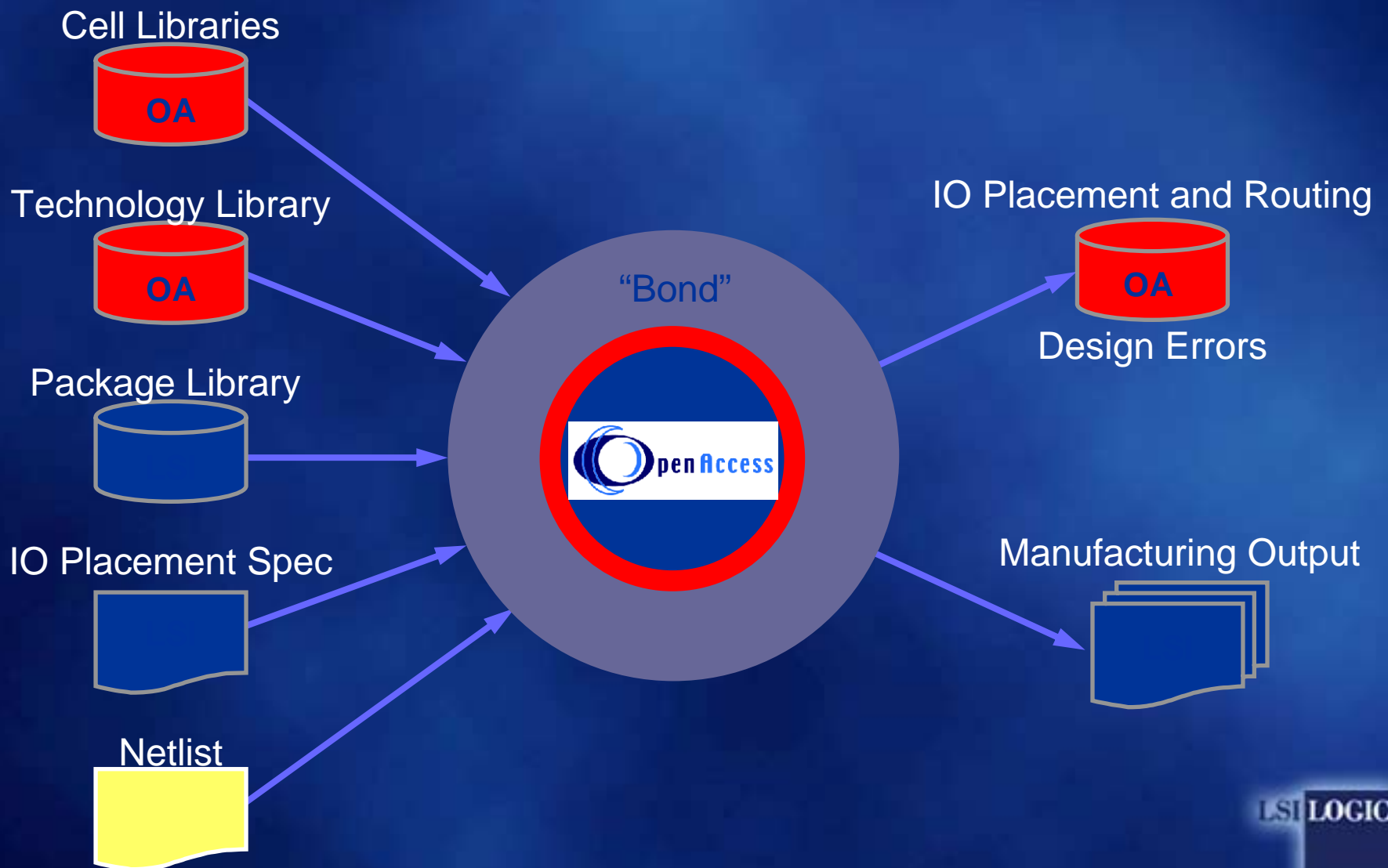
- Creation of the RapidSlice has a package bonding step
- LSI Logic created a new bonding tool based on OpenAccess
- “Bond” serves a dual role in the the creation of RapidSlices and ASICs



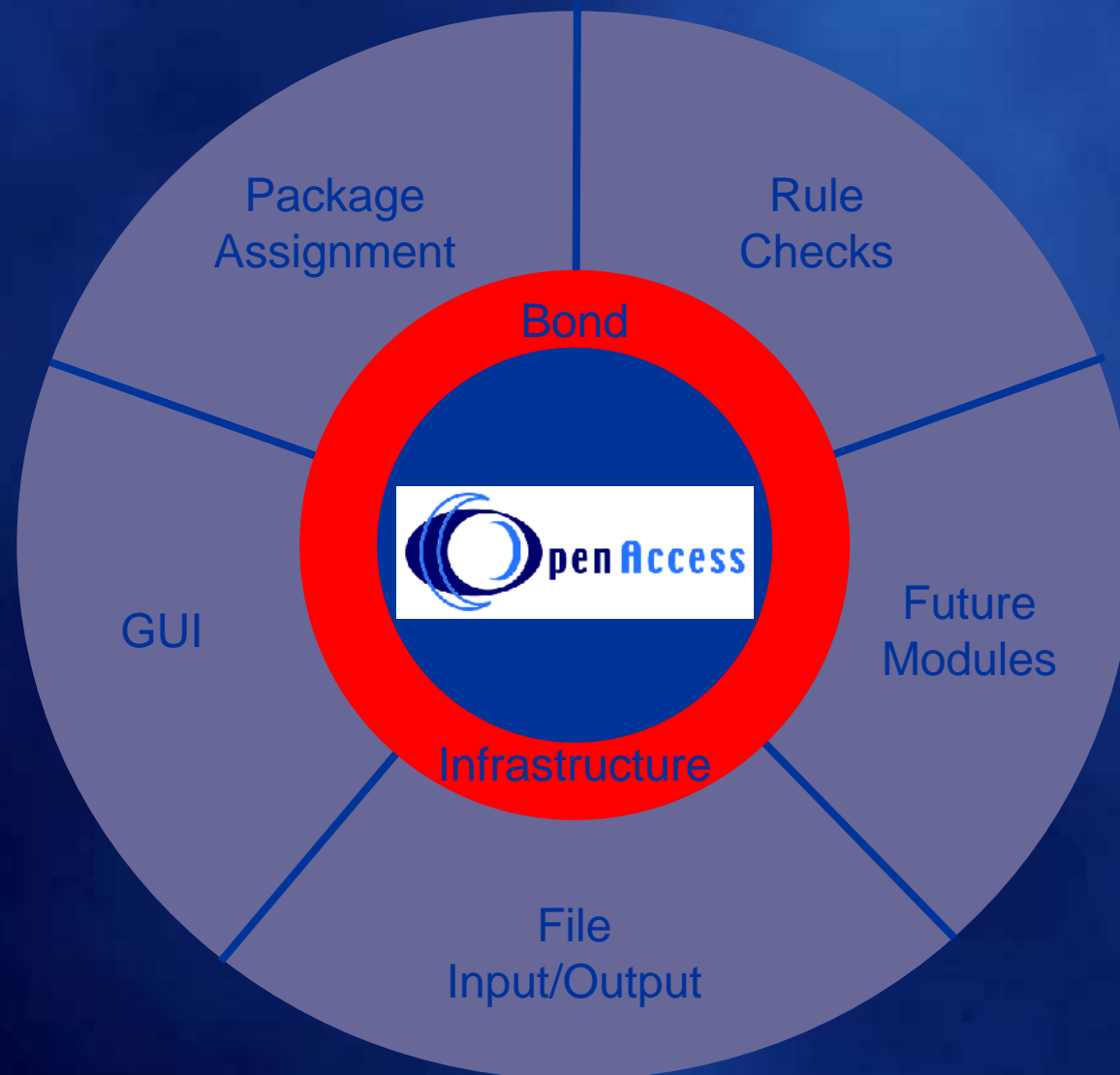
Non-OpenAccess Packaging Tool



OpenAccess Based Packaging Tool



Tool Modularity with OpenAccess



- Modules interface with each other and the main tool via a thin infrastructure.
- Module changes have little impact on other modules.
- Different developers easily work independently.



Why OpenAccess For LSI Logic?

- Source code availability
 - Debugging requires understanding the implementation
- Well defined object data model and methods
 - Enables modular development
 - Extensive API
 - Extensions
- Built-in Support for
 - Callbacks
 - Undo
 - Design Error Infrastructure
- Excellent documentation
- Scripting Interface built-in
- Open Standard
 - Not constrained by proprietary interfaces that are exclusionary
 - Permit best in class tools to work together
- Independent Control
 - Stable environment that won't change if vendors do
 - Design migration to different systems is costly
- No internal tool DB to maintain
 - No need to re-invent the wheel
 - Focus on the value-add
- Ability to make changes
 - Improves responsiveness to our customer needs



Summary

- OpenAccess has been a very positive experience for LSI
 - Its been Open
 - Its been Accessible
- No internal tool database to maintain
 - No need to re-invent the wheel
 - Focus on the value-add
 - Lowers cost
- Ability to make changes
 - Improves responsiveness to our customer needs
- Scheduled releases and Quality of deliverables have been well executed in 2003
- LSI Logic has been effective in leveraging technology
 - Silicon proven RapidChip™ is powered by OpenAccess
 - Expanding usage of OpenAccess

